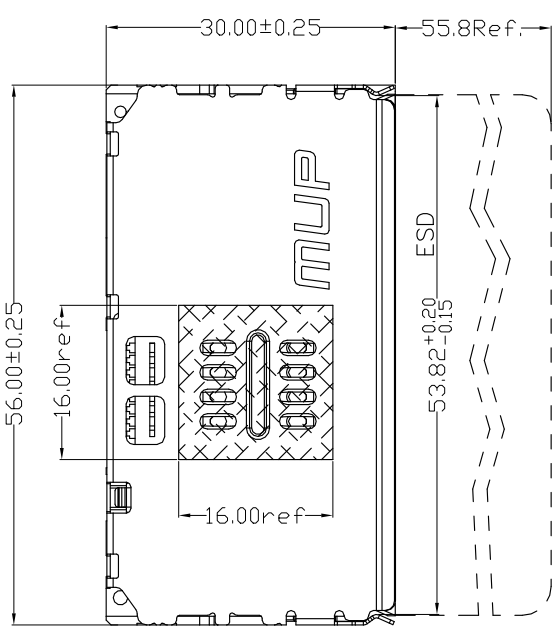
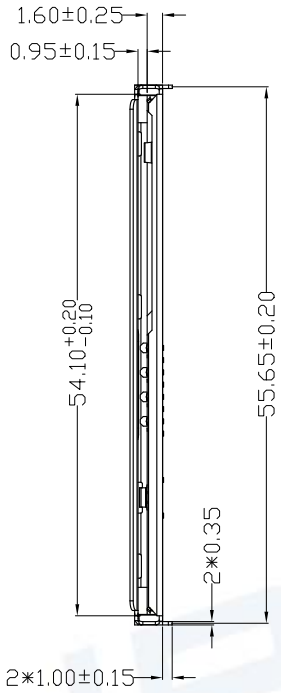
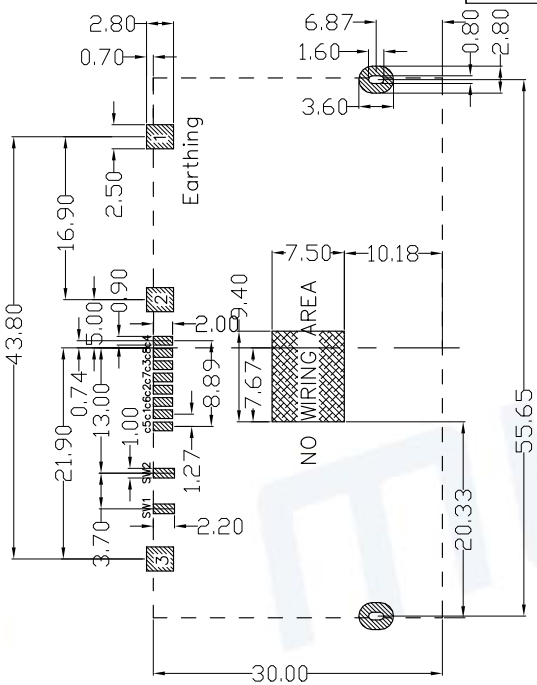
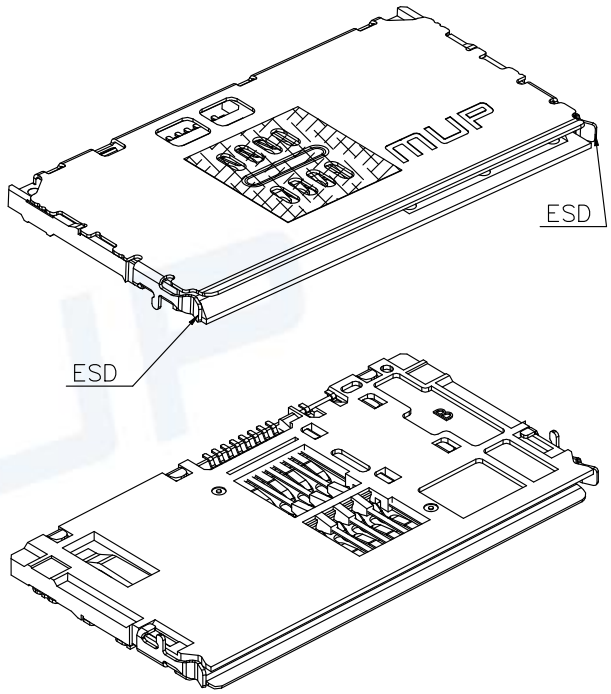
REV.	DESCRIPTION OF REVISIONS	APPR.	CHEC.	DRAW.	DATE
1	NEW			Jick	2025/01/17
2					









RECOMMENDED P.C.B LAYOUT

COMPONENT SIDE(TOLERANCE ±0.05)

Coplanarity of metal solder pins 0.15mm

Recommendating of solder paste thickness > 0.15mm

(Earthing1.2.3.)Single Solderability

PAD AREA STAND OFF AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 56.0LX30.0WX3.40H mm

Weight: Approx7.5±0.5g

Durability: 500,000 cycles min.
in a clean office room.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

IR reflow: 260°C. 10sec.Max

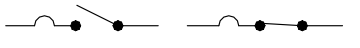
Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: −40°C~+85°C

Operating humidity: 10%~+95%RH

ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	OPEN
CARD INSERTED	CLOSED



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	SUS	Solder area: Ni
3	DATA CONTACT	8	Copper Alloy	Contact area:15u"Au plated
4	SWITCH CONTACT	1		Contact area:Silver plated
5	FLAKE	1	SUS	

Unless otherwise specified, other tolerance are:

X	±0.45	X°	±5°
X.X	±0.35	X.X°	±4°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

PROJ. | UNIT mm | SCALE 1:1

CUSTOMER DRAWING

Pb RoHS PROCESS COMPLIANT

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **Smart Card Connector**

MODEL NO: **MUP-C8079-07**

TYPE : **Normally open (Sealed SW)**

DRAWN	Jick	2025/01/17
CHECKED	Keey	2025/01/17
APPROVAL	Simon	2025/01/17

DWG NO.: DWG-C8079-07-01

SHEET 1/1 | REVISION 1